

20V N+P Dual Channel MOSFETs

General Description

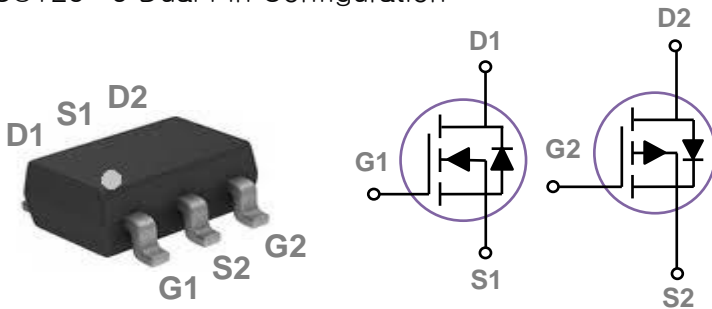
These N+P dual Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	RDSON	ID
20V	40mΩ	3.8A
-20V	100mΩ	-2.5A

Features

- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

SOT23 – 6 Dual Pin Configuration



Applications

- Notebook
- Load Switch
- Networking
- Hand-held Instruments

Absolute Maximum Ratings

Tc=25°C unless otherwise noted

Symbol	Parameter	Rating		Units
V _{DS}	Drain-Source Voltage	20	-20	V
V _{GS}	Gate-Source Voltage	± 10	±10	V
I _D	Drain Current – Continuous (T _C =25°C)	3.8	-2.5	A
	Drain Current – Continuous (T _C =100°C)	2.3	-1.5	A
I _{DM}	Drain Current – Pulsed ¹	15.2	-10	A
P _D	Power Dissipation (T _C =25°C)	1.25	1.25	W
	Power Dissipation – Derate above 25°C	0.01	0.01	W/°C
T _{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
T _J	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R _{θJA}	Thermal Resistance Junction to ambient	---	100	°C/W



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N-CH Electrical Characteristics (T_J=25 °C, unless otherwise)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	20	---	---	V
ΔBV _{DSS} /ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.02	---	V/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =20V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =16V, V _{GS} =0V, T _J =125°C	---	---	10	uA
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±10V, V _{DS} =0V	---	---	±100	nA

On Characteristics

R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =4.5V, I _D =3A	---	30	40	mΩ
		V _{GS} =2.5V, I _D =2A	---	42	55	mΩ
		V _{GS} =1.8V, I _D =1.5A	---	55	70	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	0.3	0.6	1	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-2	---	mV/°C
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =2A	---	4.4	---	S

Dynamic and switching Characteristics

Q _g	Total Gate Charge ^{2,3}	V _{DS} =10V, V _{GS} =4.5V, I _D =3A	---	5.8	10	nC
Q _{gs}	Gate-Source Charge ^{2,3}		---	0.6	1.5	
Q _{gd}	Gate-Drain Charge ^{2,3}		---	1.5	3	
T _{d(on)}	Turn-On Delay Time ^{2,3}	V _{DD} =10V, V _{GS} =4.5V, R _G =25Ω I _D =1A	---	2.9	6	ns
T _r	Rise Time ^{2,3}		---	8.4	16	
T _{d(off)}	Turn-Off Delay Time ^{2,3}		---	19.2	38	
T _f	Fall Time ^{2,3}		---	5.6	12	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, F=1MHz	---	315	600	pF
C _{oss}	Output Capacitance		---	50	80	
C _{riss}	Reverse Transfer Capacitance		---	40	60	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current	V _G =V _D =0V, Force Current	---	---	3.8	A
I _{SM}	Pulsed Source Current		---	---	7.6	A
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =1A, T _J =25°C	---	---	1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
3. Essentially independent of operating temperature.

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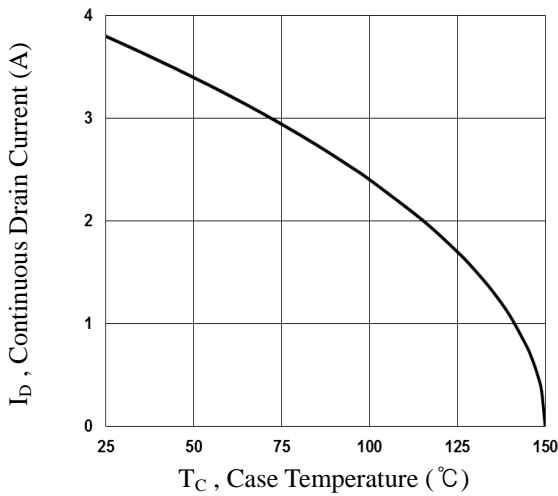


Fig. 1 Continuous Drain Current vs. T_C

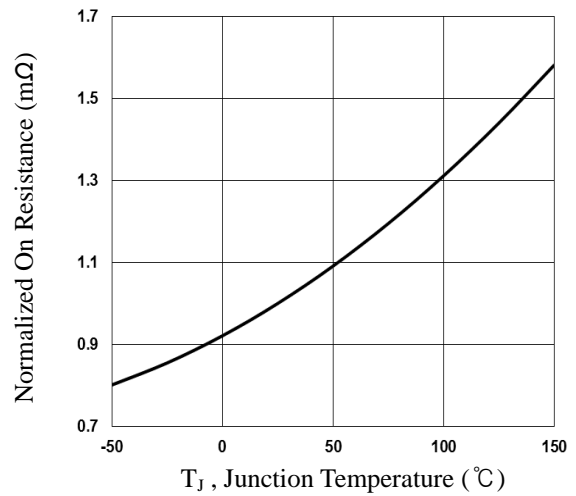


Fig. 2 Normalized $R_{DS(on)}$ vs. T_J

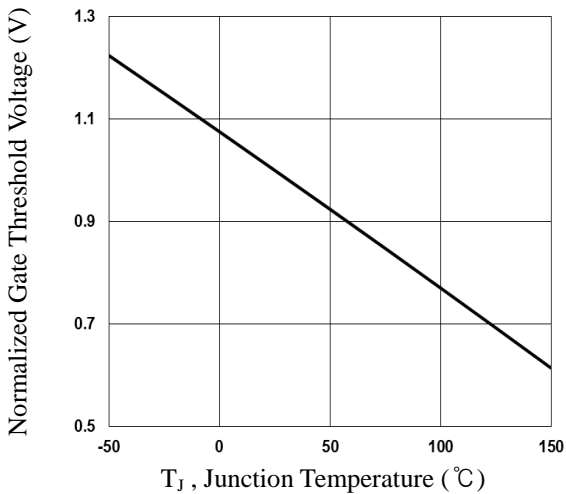


Fig. 3 Normalized V_{th} vs. T_J

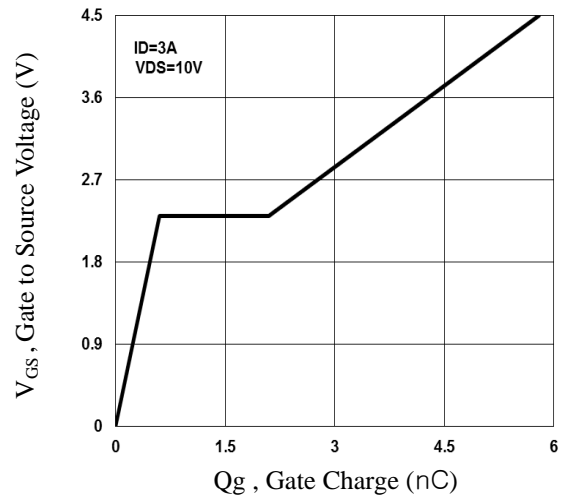


Fig. 4 Gate Charge Waveform

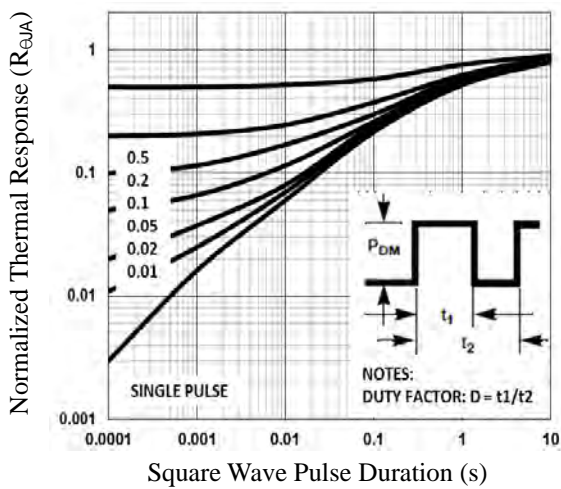


Fig. 5 Normalized Transient Impedance

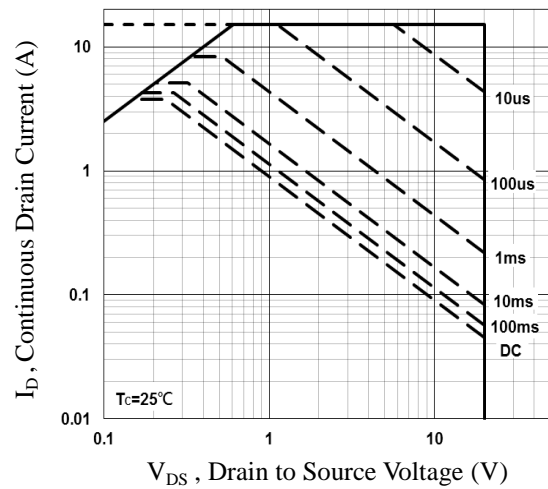


Fig. 6 Maximum Safe Operation Area



FTK2116NP

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P-CH Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-20	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=-1mA$	---	-0.01	---	V/ $^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-20V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	μA
		$V_{DS}=-16V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	-10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 10V, V_{DS}=0V$	---	---	± 100	nA

On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-4.5V, I_D=-3A$	---	82	100	m Ω
		$V_{GS}=-2.5V, I_D=-2A$	---	125	140	m Ω
		$V_{GS}=-1.8V, I_D=-1A$	---	197	230	m Ω
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-0.3	-0.6	-1.0	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	3	---	mV/ $^\circ\text{C}$
gfs	Forward Transconductance	$V_{DS}=-10V, I_D=-1A$	---	2.2	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2,3}	$V_{DS}=-10V, V_{GS}=-4.5V, I_D=-2A$	---	4.8	10	nC
Q_{gs}	Gate-Source Charge ^{2,3}		---	0.5	1	
Q_{gd}	Gate-Drain Charge ^{2,3}		---	1.9	4	
$T_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=-10V, V_{GS}=-4.5V, R_G=25\Omega$ $I_D=-1A$	---	3.5	7	ns
T_r	Rise Time ^{2,3}		---	12.6	24	
$T_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	32.6	62	
T_f	Fall Time ^{2,3}		---	8.4	16	
C_{iss}	Input Capacitance	$V_{DS}=-15V, V_{GS}=0V, F=1MHz$	---	350	510	pF
C_{oss}	Output Capacitance		---	65	95	
C_{rss}	Reverse Transfer Capacitance		---	50	75	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current	$V_G=V_D=0V$, Force Current	---	---	-2.5	A
I_{SM}	Pulsed Source Current		---	---	-5	A
V_{SD}	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1	V

Note :

4. Repetitive Rating : Pulsed width limited by maximum junction temperature.
5. The data tested by pulsed, pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
6. Essentially independent of operating temperature.

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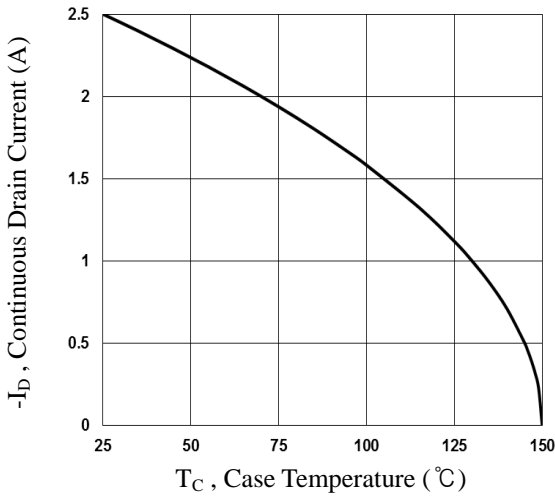


Fig. 7 Continuous Drain Current vs. T_c

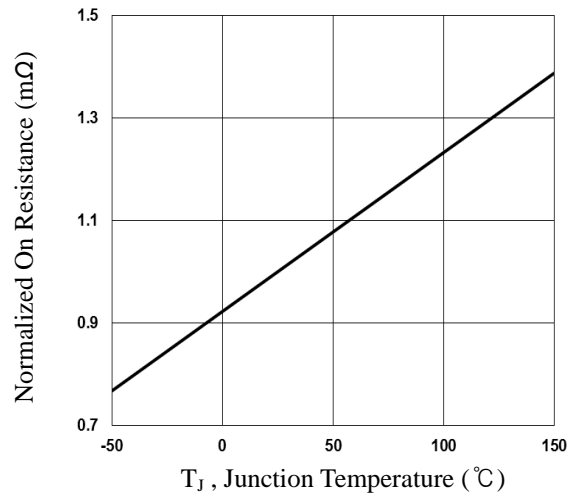


Fig. 8 Normalized $R_{DS(on)}$ vs. T_j

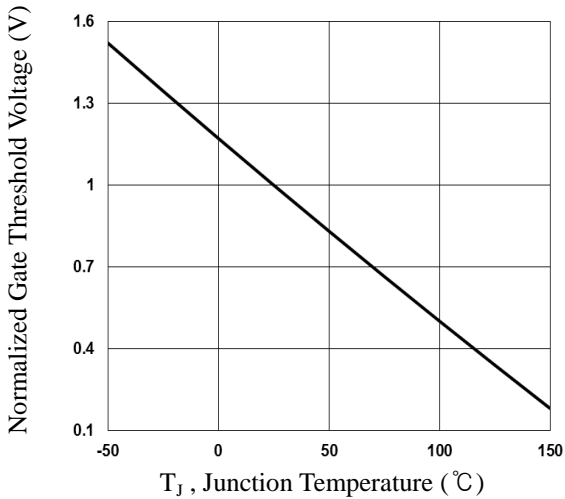


Fig. 9 Normalized V_{th} vs. T_j

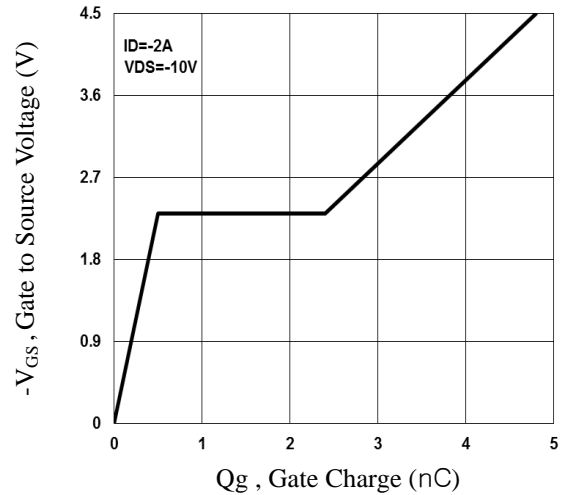


Fig. 10 Gate Charge Waveform

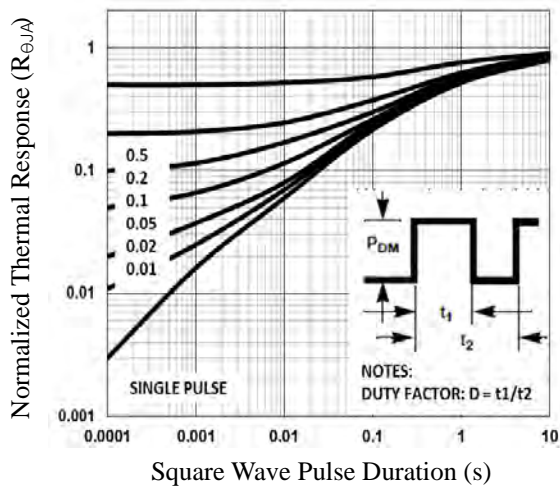


Fig. 11 Normalized Transient Impedance

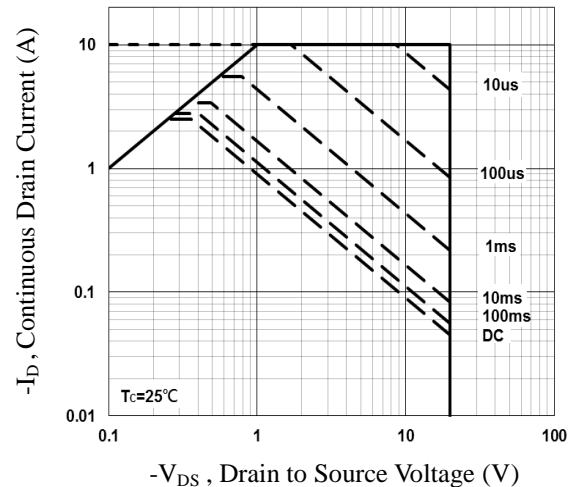
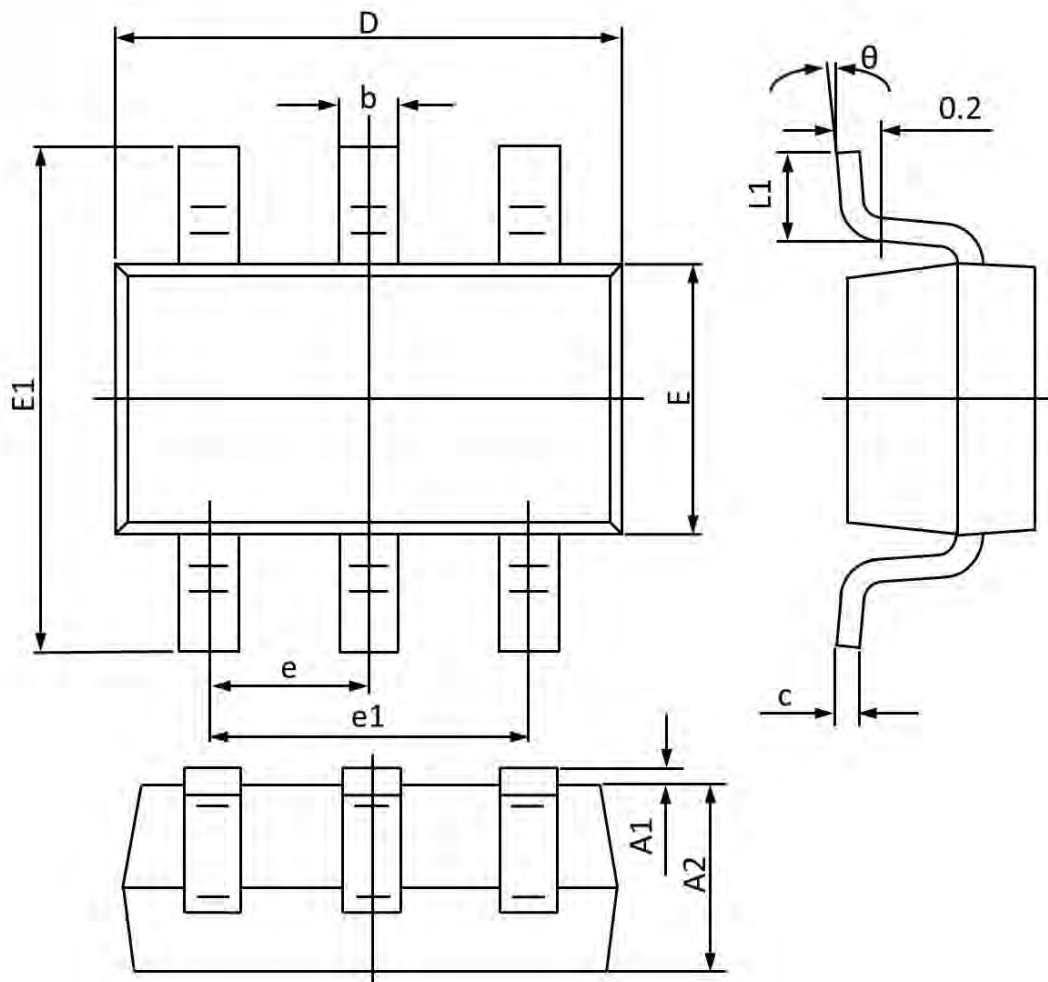


Fig. 12 Maximum Safe Operation Area

SOT23-6 Dual PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.040	0.047
b	0.300	0.500	0.012	0.019
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E	1.500	1.800	0.059	0.070
E1	2.600	3.000	0.103	0.118
e	0.950 TYP		0.037 TYP	
e1	1.900 TYP		0.075 TYP	
L1	0.250	0.550	0.010	0.021
θ	0°	8°	0°	8°